

**FULL-WAFER OR LARGE AREA IMPRINTING WITH
MULTIPLE SEPARATED SUB-FIELDS FOR HIGH
THROUGHPUT LITHOGRAPHY**

ABSTRACT OF THE DISCLOSURE

[0040] The present invention is directed to a method of forming a layer on a substrate comprising forming a plurality of flowable regions on the substrate and contacting the flowable regions with a plurality of molds disposed on a template. Thereafter, the plurality of flowable regions is solidified. In a further embodiment, the method further includes spreading each of the plurality of flowable regions to an area.